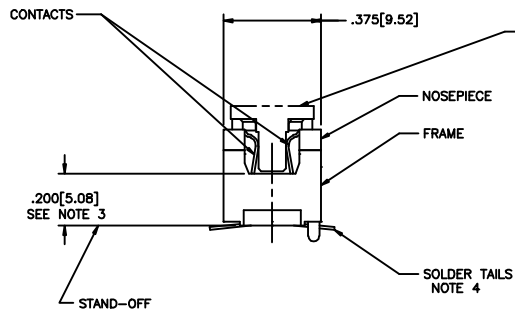
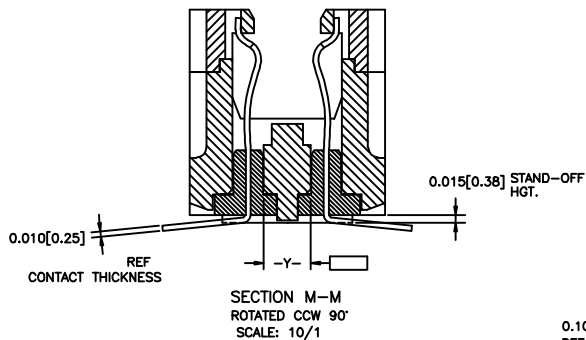
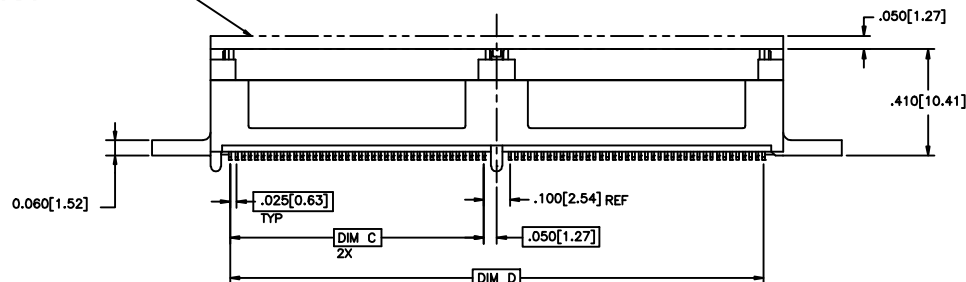
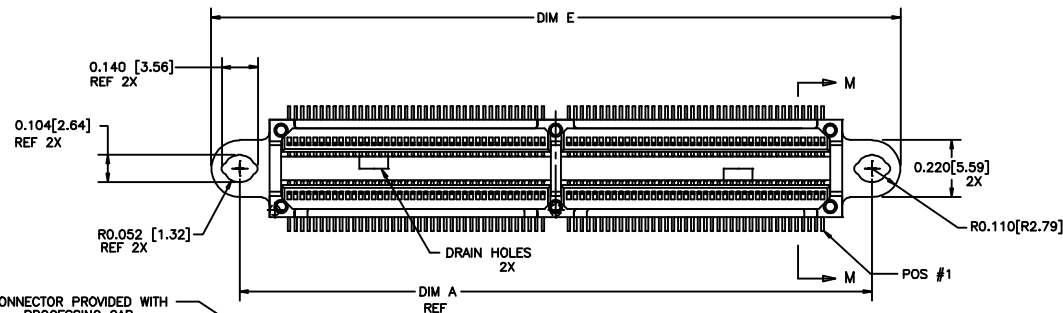
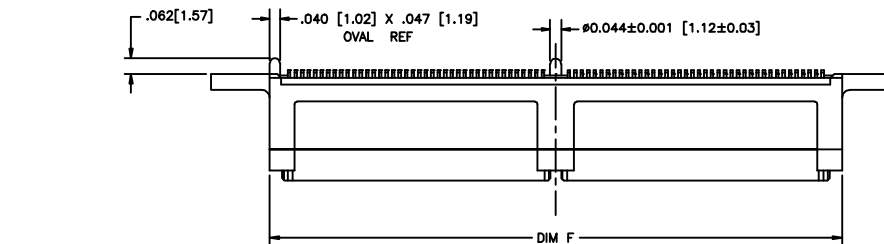


PRODUCT NUMBER

SEE TABLE



CONNECTOR PROVIDED WITH
PROCESSING CAP
NOTE 5

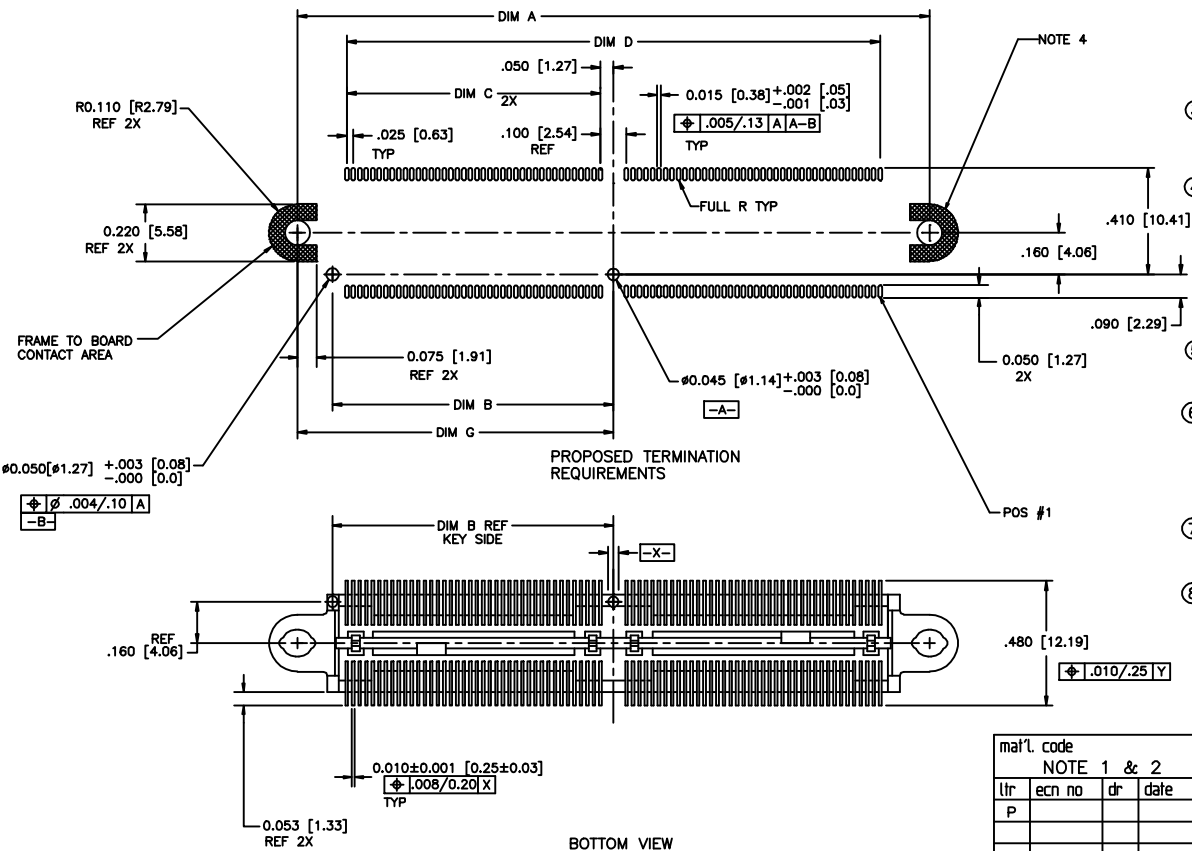


mat'l. code	NOTE 1 & 2	surface	ISO 1302	tolerance	ISO 406 ISO 1101	projection	product family
litr	ec'n no	dr	date	tolerances unless otherwise specified			MICROPAX
H	C70095	SAR	7/22/97	angles	linear	INCH/MM	title
J	B81703	EPK	9/25/98				.025M SURFACE MOUNT
K	V12473	MEM	10/10/01	0'±2'		scale 1:1	RECEPT., DOUBLE MODULE
L	V12650	MEM	11/02/01	dr	M. HERNANDEZ	11/17/04	dwg no
M	M04-0216	MHT	11/17/04	engr	F. SALAS	11/17/04	sheet 1 of 2 size
N	M06-0279	AEA	7/22/06	chr	F. SALAS	11/17/04	91403 A3
P	M08-0271	MHT	9/25/08	appd	F. SALAS	11/17/04	type Product Customer Drawing
sheet	revision	P	P				
index	sheet	1	2				

PRODUCT NUMBER	NO. OF CONTACTS	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G	CONTACT PLATING NOTE 2
91403-001	120	1.930/49.02	.830/21.08	.725/18.42	1.550/39.37	2.150/54.61	1.700/43.18	.965/24.51	30 GXT
91403-001LF									
91403-002	160	2.430/61.72	1.080/.27.43	.975/24.76	2.050/52.07	2.650/67.31	2.200/55.88	1.215/30.86	30 GXT
91403-002LF									
91403-003	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.700/68.58	1.465/37.21	30 GXT
91403-003LF									
91403-403	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.700/68.58	1.465/37.21	60 GXT
91403-403LF									

NOTES:

- MATERIALS:**
DIELECTRIC: LCP
CONTACTS: BeCu
FRAME: ZINC ALLOY #3
- PLATING:**
SOLDER TAILS:
TIN LEAD: 150u"/3.81um Sn Pb
LEAD FREE OPTION: 150u"/3.81um Sn
FRAME: 100u"/2.54um Ni
CONTACTS: 30u"/.76um GXT OVER 50u"/1.27um Ni
OR 60u"/1.52um GXT OVER 75u"/1.90um Ni.
- WHEN THE CONNECTOR IS MATED WITH THE OPPOSITE HALF, THE PARALLEL BD. TO BD. HGT. IS .47 ±.01. (APPLYS TO VERT. THRU & SURFACE MT. STYLES)
- THE SOLDER TAILS ON THIS PRODUCT ARE DESIGNED TO BE COMPLIANT IN ORDER TO ACCOMMODATE PRINTED CIRCUIT BOARD DIMENSIONAL VARIATIONS. THEREFORE, HOLDDOWN HARDWARE IS REQUIRED TO SECURE THE CONNECTOR TO THE PRINTED CIRCUIT BOARD FOR MOST TYPES OF SOLDER REFLOW OPERATIONS. FOR FURTHER APPLICATION DATA, INCLUDING HOLE SIZES FOR VARIOUS TYPES OF HARDWARE, SEE TA-932.
- DO NOT REMOVE PROCESSING CAP UNTIL SOLDERING IS COMPLETED. CAP WILL PREVENT POTENTIAL NOSE PIECE BOW DURING HIGH TEMP. SOLDERING PROCESS.
- PART NUMBERS WITH LF IN THE END ARE LEAD FREE OPTION.
EXAMPLE: 91403-XXX LF
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 20 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.



mat'l. code	surface	tolerance	projection	product family
NOTE 1 & 2	ISO 1302	ISO 406		MICROPAX
ltr	ecn no	dr	date	title
P				.025M SURFACE MOUNT RECEPT., DOUBLE MODULE
	angles	linear	XX±.01/XX±.03	INCH/MM
	0'±2'		XXX±.005/XXX±.013	scale 1:1
	dr	M. HERNANDEZ	11/17/04	dwg no
	engr	F. SALAS	11/17/04	sheet 2 of 2 size
	chr	F. SALAS	11/17/04	91403
	appd	F. SALAS	11/17/04	A3
sheet index	revision	sheet		type
				Product Customer Drawing